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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

13
92

APPL NUM 10034030	FILING DATE 12/19/2001	CLASS 029 438	SUBCLASS 854	GAU 3729 2812	EXAMINER Trinh D. Nguyen
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**APPLICANTS: Horng Gwo-Ji; Kuo Jen-I; Hsiao Feng-Ge;

**CONTINUING DATA VERIFIED:

None (mf)

** FOREIGN APPLICATIONS VERIFIED:

None (mf)

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed

☐ yes ☒ no

35 USC 119 conditions met

☐ yes ☒ no

Verified and Acknowledged Examiners's initials

[Signature]

ATTORNEY DOCKET NO

JCLA8482

TITLE : Method of fabricating a ceramic substrate with a thermal conductive plug of a multi-chip package

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Shoots Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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